Tool ID: 125
Tool Location: 111

Equipment Information Sheet

RTA - AG610b

Manager: Michael Skvarla 607-254-4674
Backup: Phil Infante 607-254-4926
Backup: Aaron Windsor 607-254-4831

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- High temperature / power presents risks to tool and samples - Double check everything!

USAGE RESTRICTIONS
SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 0 minutes

- Reserve no more than 2 hours from 9 AM - 5 PM - See the instrument manager if you need more time

MATERIALS COMPATIBILITY CATEGORY

Tool Category 2: Silicon Based Substrates and Select Refractory Metals

Allowed	Not Allowed
Tool category 1/1E materials	No Glass Substrates
Silicon Based Materials only	No CNF Class A or Class B metals and oxides/compounds of (exposed or buried) (ie Magnesium, Zinc, Barium, Calcium)
Si, SiC, SiO_2 substrates	
All Furnace grown or deposited films	
PECVD Films	No Gold, Silver or Copper (Exposed or buried)
ALD dieletric films	No High Vapor pressure materials
CNF Refractory Metals (ie Al, Ti,Ta,W,Pt,Mo,Cr,Ni)	No III/V Compound Semiconductors
Nitrides and Oxides of above metals	No Organic/Biology Molecules prepared-with or without Salt buffers
Cured organics and baked Photoresist	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No samples with resist, glue, metals, or anything that may degas - Calibrated for whole Silicon wafers - Discuss pieces or other materials with tool manager

Last Updated: 11/28/2018